

Microsemi Corporation: PCN19007

March 29, 2019

Product/Process Change Notification No: PCN19007

Change Classification: Major

Subject

ProASIC3, IGLOO, Fusion, SmartFusion, ProASIC Plus, MX, and AX Family Devices—Change of Mold Compound and Die-Attach Epoxy

Description of Change

Devices listed in this PCN will change their mold compound and die-attach epoxy materials. There is no change to the device form, fit, or function.

The following table describes the material changes.

	From	To
Mold compound	Shin-Etsu KMC2520AL	Kyocera KE-G1250LKD-30
Die attach epoxy	Sumitomo CRM-1525D and Ablestik A2000	Sumitomo CRM-1076WB

Reason for Change

Microsemi's subcontract assembly facility UTAC, located in Dongguan China, is phasing out the legacy mold compound and die-attach epoxy materials.

Devices that currently utilize these legacy materials will start using the current standard halide-free assembly materials used by UTAC China for BGA packages.

Only the devices that are being assembled in UTAC in BGA packages and utilizing gold-bond wires are affected. Devices that are currently being built with copper wire (palladium-coated copper wire) have been using UTAC's standard halide-free materials since 2012 and are not affected. See [PCN1201D](#) for information about devices that were converted to copper wire.

Any device on the Affected Parts List in [PCN1201D](#) that the customer had a special request for assembly lot with Au bond wire (special builds only) still utilized the legacy mold compound and epoxy. As of March 29th, these special builds will also be supported with the current standard halide-free assembly materials.

Application Impact

There is no expected impact to customer applications.

Products Affected by this Change

See [Appendix A](#).

Production Shipment Schedule

Microsemi may begin shipping parts with the new mold compound and die-attach epoxy materials starting June 27, 2019.

Microsemi reserves the right to continue the shipment of devices with the legacy materials until the inventory is depleted.

Customers may receive a mix of pre-conversion products (legacy mold compound and epoxy) and products with the current standard halide-free mold compound and epoxy.

Qualification Data

Qualification report is available upon request.

Contact Information

Contact Microsemi's Technical Support department using the support portal at <https://soc.microsemi.com/Portal/Default.aspx>.

Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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PCN19007 Appendix A

The following table lists the part numbers affected by PCN19007.

Table 1 • Affected Parts List

A2F200M3F-1CS288I	A2F200M3F-1CSG288I	A2F200M3F-1FG256I	A2F200M3F-1FGG256	A2F200M3F-1FGG256I
A2F200M3F-CS288	A2F200M3F-CS288I	A2F200M3F-CSG288	A2F200M3F-CSG288I	A2F200M3F-FG256
A2F200M3F-FG256I	A2F200M3F-FGG256	A2F200M3F-FGG256I	A2F500M3G-1CS288	A2F500M3G-1CS288I
A2F500M3G-1CSG288I	A2F500M3G-1FG256I	A2F500M3G-1FG256M	A2F500M3G-1FGG256	A2F500M3G-1FGG256I
A2F500M3G-CS288I	A2F500M3G-CSG288	A2F500M3G-CSG288I	A2F500M3G-FG256I	A2F500M3G-FG256M
A2F500M3G-FGG256	A2F500M3G-FGG256I	A2F500M3G-FGG256M	A3P1000-1FG144	A3P1000-1FG144I
A3P1000-1FG144M	A3P1000-1FG256	A3P1000-1FG256M	A3P1000-1FG256T	A3P1000-1FGG144
A3P1000-1FGG144I	A3P1000-1FGG144M	A3P1000-1FGG256I	A3P1000-2FG144I	A3P1000-2FG256I
A3P1000-2FG256M	A3P1000-2FGG144	A3P1000-2FGG144I	A3P1000-2FGG256I	A3P1000-FG144
A3P1000-FG144I	A3P1000-FG144M	A3P1000-FG144T	A3P1000-FG256	A3P1000-FG256I
A3P1000-FG256M	A3P1000-FG256T	A3P1000-FGG144	A3P1000-FGG144I	A3P1000-FGG144M
A3P1000-FGG144T	A3P1000-FGG256	A3P1000-FGG256I	A3P1000-FGG256M	A3P1000-FGG256T
A3P1000L-1FG144I	A3P1000L-1FG256I	A3P1000L-1FGG144I	A3P1000L-1FGG256I	A3P1000L-FG144I
A3P1000L-FG256	A3P1000L-FG256I	A3P1000L-FGG144	A3P1000L-FGG144I	A3P1000L-FGG256
A3P1000L-FGG256I	A3P125-1FGG144	A3P125-1FGG144I	A3P125-2FG144I	A3P125-FG144
A3P125-FG144I	A3P125-FG144T	A3P125-FGG144	A3P125-FGG144I	A3P250-1FG144I
A3P250-1FG144M	A3P250-1FGG144	A3P250-1FGG144I	A3P250-2FG144I	A3P250-2FG256I
A3P250-2FGG144	A3P250-2FGG144I	A3P250-2FGG256	A3P250-2FGG256I	A3P250-FG144
A3P250-FG144I	A3P250-FG144T	A3P250-FG256	A3P250-FG256I	A3P250-FGG144
A3P250-FGG144I	A3P250-FGG144T	A3P250-FGG256	A3P250-FGG256I	A3P250L-1FGG144I
A3P250L-1FGG256I	A3P250L-FG256I	A3P250L-FGG144	A3P250L-FGG144I	A3P250L-FGG256
A3P250L-FGG256I	A3P400-1FGG144	A3P400-1FGG256	A3P400-2FG144I	A3P400-2FG256I
A3P400-2FGG144I	A3P400-2FGG256I	A3P400-FG144	A3P400-FG144I	A3P400-FG256
A3P400-FG256I	A3P400-FGG144	A3P400-FGG144I	A3P400-FGG256	A3P400-FGG256I
A3P600-1FG256I	A3P600-1FGG144	A3P600-2FG144I	A3P600-2FG256I	A3P600-2FGG144
A3P600-2FGG144I	A3P600-2FGG256	A3P600-2FGG256I	A3P600-FG144	A3P600-FG144I
A3P600-FG256	A3P600-FG256I	A3P600-FGG144	A3P600-FGG144I	A3P600-FGG256
A3P600-FGG256I	A3P600L-1FG256I	A3P600L-1FGG144	A3P600L-1FGG144I	A3P600L-FG256I
A3P600L-FGG144	A3P600L-FGG144I	A3PE3000-1FG324I	A3PE3000-1FGG324	A3PE3000-2FG324I
A3PE3000-2FGG324I	A3PE3000-FG324	A3PE3000-FG324I	A3PE3000-FGG324	A3PE3000L-1FG324I
A3PE3000L-1FGG324	A3PE3000L-1FGG324I	A3PE3000L-FG324	A3PE3000L-FG324I	A3PE3000L-FGG324I
A3PE600-2FG256I	A3PE600-2FGG256I	A3PE600-FG256I	A3PE600-FGG256	A3PE600-FGG256I
A42MX36-2BG272I	A42MX36-BG272	A42MX36-BG272I	A42MX36-BG272M	A42MX36-BGG272I
AFS090-FGG256	AFS090-FGG256I	AFS1500-1FG256I	AFS1500-2FG256I	AFS1500-FG256I
AFS1500-FG256K	AFS1500-FGG256	AFS1500-FGG256I	AFS250-1FGG256	AFS250-FG256I

AFS250-FGG256	AFS250-FGG256I	AFS600-1FG256I	AFS600-1FG256K	AFS600-FG256
AFS600-FG256I	AFS600-FG256K	AFS600-FGG256	AFS600-FGG256I	AFS600-FGG256K
AGL1000V2-CS281I	AGL1000V2-CSG281	AGL1000V2-CSG281I	AGL1000V2-FG144	AGL1000V2-FG144I
AGL1000V2-FG256I	AGL1000V2-FGG144	AGL1000V2-FGG144I	AGL1000V2-FGG256I	AGL1000V5-CSG281
AGL1000V5-CSG281I	AGL1000V5-FG144	AGL1000V5-FG144I	AGL1000V5-FG256I	AGL1000V5-FGG144
AGL1000V5-FGG144I	AGL1000V5-FGG256	AGL1000V5-FGG256I	AGL125V2-FG144I	AGL125V2-FGG144
AGL125V2-FGG144I	AGL125V5-FG144I	AGL125V5-FGG144	AGL125V5-FGG144I	AGL250V2-FG144I
AGL250V2-FGG144	AGL250V2-FGG144I	AGL250V5-FG144I	AGL250V5-FGG144	AGL250V5-FGG144I
AGL400V2-FG256I	AGL400V2-FGG144	AGL400V2-FGG144I	AGL400V2-FGG256I	AGL400V5-FG144
AGL400V5-FG144I	AGL400V5-FG256I	AGL400V5-FGG144	AGL400V5-FGG144I	AGL400V5-FGG256
AGL400V5-FGG256I	AGL600V2-CS281I	AGL600V2-CSG281	AGL600V2-CSG281I	AGL600V2-FG144
AGL600V2-FG144I	AGL600V2-FG256I	AGL600V2-FGG144	AGL600V2-FGG144I	AGL600V2-FGG256
AGL600V2-FGG256I	AGL600V5-CS281I	AGL600V5-CSG281	AGL600V5-CSG281I	AGL600V5-FG144I
AGL600V5-FG256I	AGL600V5-FGG144	AGL600V5-FGG144I	AGL600V5-FGG256	AGL600V5-FGG256I
AGLP125V2-CS281I	AGLP125V2-CSG281	AGLP125V2-CSG281I	AGLP125V5-CS281I	AGLP125V5-CSG281
AGLP125V5-CSG281I	APA075-FG144	APA075-FG144I	APA075-FGG144	APA075-FGG144I
APA150-FG144I	APA150-FG256	APA150-FG256I	APA150-FGG144	APA150-FGG144I
APA150-FGG256	APA150-FGG256I	APA300-FG144I	APA300-FG144M	APA300-FG256
APA300-FG256I	APA300-FG256M	APA300-FGG144	APA300-FGG144I	APA300-FGG256
APA300-FGG256I	APA450-FG144I	APA450-FG256	APA450-FG256I	APA450-FGG144I
APA450-FGG256	APA450-FGG256I	APA600-FG256	APA600-FG256I	APA600-FG256M
APA600-FGG256I	AX250-1FG256I	AX250-1FGG256M	AX250-2FG256I	AX250-2FGG256I
AX250-FG256	AX250-FG256I	AX250-FG256M	AX250-FGG256I	M1A3P1000-2FGG256I
M1A3P1000-FG256I	M1A3P1000L-FG256I	M1A3P600-FGG256I	M1AFS1500-2FG256I	M1AFS1500-FGG256
M1AGL1000V2-CS281I	M1AGL1000V2-CSG281I	M1AGL1000V2-FG144	M1AGL1000V2-FG144I	M1AGL1000V2-FGG144I
M1AGL1000V2-FGG256	M1AGL1000V2-FGG256I	M1AGL1000V5-FGG144I	M1AGL250V5-FG144I	M1AGL600V5-FGG256
P1AFS1500-2FG256	P1AFS600-2FG256I	P1AFS600-2FGG256I		



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